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Attorney Docket Number: 511.37656X00
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Sir:

Attached please find the application papers of Toshihisa KUMAKURA, Takeshi HORIUCHI, Kazuyuki MAGOME, Norifumi SHIRAISHI, covering new and useful improvements in ADHESIVE COMPOSITION FOR METAL FOIL, AND ADHESIVE-COATED METAL FOIL, METAL-CLAD LAMINATE AND RELATED MATERIALS USING THE SAME, comprising:

Specification, Eighteen (18) Claims and Abstract of the Disclosure (33 pages)

English language, Combined Declaration and Power of Attorney (2 pages)

Assignment and Recording of Assignment Letter

U.S. Government Filing Fee of \$1,098.00

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Change of Correspondence Address

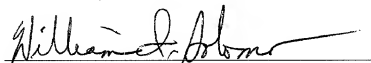
PTO 1449 Form With Attached References

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Please charge any shortages in the fees or credit any overpayments thereof to the deposit account of Antonelli, Terry, Stout & Kraus, LLP Account No. 01-2135 (511.37656X00).

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

A handwritten signature in dark ink, appearing to read "William I. Solomon", is written over a horizontal line.

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Registration No. 28,565

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Attachments

FP2328

ADHESIVE COMPOSITION FOR METAL FOIL, AND ADHESIVE-COATED
METAL FOIL, METAL-CLAD LAMINATE AND RELATED MATERIALS
5 USING THE SAME

BACKGROUND OF THE INVENTION

1. Field of the invention

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This invention relates to an adhesive composition for a metal foil to be used for preparation of a laminated plate for a printed wiring board to be used for an electric and electronic equipment, an adhesive-coated metal foil, a
15 metal-clad laminate, a wiring board, a multi-layer board and a multi-layer wiring board using the same.

2. Background art

20 Electronic equipment for public use becomes a small size and has high functions so that a printed wiring board to be used therein is required to be high density and fine wiring pattern. Accompanying with this tendency, a copper-clad laminate to be used in a printed wiring board
25 is required to be high density when it is actually fit. Thus, required levels of solder heat resistance or copper foil-peel resistance is becoming severer. Also, for electric equipment to which a high voltage is applied such as a television set, tracking resistance is now required
30 to ensure safety. Tracking means a phenomenon, which forms a carbonized conducting path or a tracking path between the portions having a difference in voltage on the surface of an insulating material.

35 In the prior art, a copper clad laminated board has been prepared by adhering an adhesive-coated metal foil in

which an adhesive layer is formed on a copper foil and a prepreg in order to improve adhesiveness between the copper foil of the copper clad laminated board and the prepreg. As the adhesive, an adhesive in which a phenol resin is formulated into a polyvinyl acetal resin has been used since it is excellent in the points of adhesiveness, solder heat resistance and copper foil peel resistance.

- However, in an adhesive in which a phenol resin is formulated into a polyvinyl acetal resin, whereas solder heat resistance, etc. are excellent, but the phenol resin is easily carbonized so that the adhesive becomes easily conductive whereby it is inferior in tracking resistance.
- Thus, to improve tracking resistance of an adhesive, a method of using an epoxy resin or a melamine resin has been proposed, for example, in Japanese Provisional Patent Publication No. 116682/1987.
- However, only when an epoxy resin or a melamine resin is formulated into an adhesive, the tracking resistance cannot sufficiently be improved. And yet, as compared with the case where a phenol resin is formulated, reactivity or compatibility of a resin is markedly different so that heat resistance can hardly be maintained.

SUMMARY OF THE INVENTION

- An object of the present invention is to provide an adhesive composition for a metal foil having excellent heat resistance and tracking resistance by solving the above problems and having good laminated board characteristics, an adhesive-coated metal foil, a metal-clad laminate, a wiring board, a multi-layer board and a multi-layer wiring board using the same.

The present invention relates to an adhesive composition for a metal foil which comprises a material wherein a tracking resistance test is carried out according to the IEC method by making a thickness of an adhesive layer 30
5 to 40 μm , using a copper foil pattern with a width of 4 mm and making a distance between electrodes 0.4 mm, then the adhesive layer dissolves out for the first time when 5 drops or more of an electrolyte are dropped thereon.

- 10 Moreover, the present invention relates to an adhesive composition for a metal foil, which comprises a polyvinyl acetal resin and a thermosetting resin.

The present invention also relates to an adhesive composition for a metal foil which comprises a polyvinyl acetal resin and a thermosetting resin and in a thermogravimetric analysis after curing, a 5 % weight loss temperature being 290°C or more and a carbon residual ratio at 650°C being less than 1 % by weight.

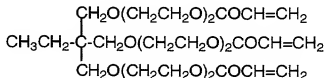
- 20 Further, the present invention relates to an adhesive composition for a metal foil which comprises thermosetting resins at least one of which does not react with a polyvinyl acetal resin and which is compatible with the polyvinyl acetal resin uniformly. Moreover, the present
25 invention relates to an adhesive composition for a metal foil which comprises thermosetting resins at least one of which does not have an aromatic ring.

- 30 The present invention further relates to an adhesive composition for a metal foil which comprises thermosetting heat-resistant resins at least one of which is at least one of a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl
35 groups or methacryloyl groups in the molecule.

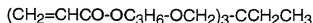
The present invention further relates to the above-mentioned adhesive composition for a metal foil which comprises as main components a polyvinyl acetal resin, a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule and an epoxy resin.

The present invention further relates to the above-mentioned adhesive composition for a metal foil which comprises 20 to 500 parts by weight of a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule and 5 to 100 parts by weight of an epoxy resin based on 100 parts by weight of a polyvinyl acetal resin.

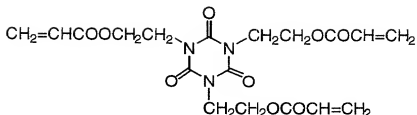
Moreover, the present invention relates to the above-mentioned adhesive composition for a metal foil wherein the polyfunctional acrylate compound or the polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule is at least one selected from the group consisting of pentaerythritol triacrylate, trimethylolpropane triacrylate, trimethylolpropane ethyleneoxide triacrylate represented by the formula:



trimethylolpropane propyleneoxide triacrylate represented by the formula:



triacryloyloxyethyl phosphate, isocyanuric acid ethylene oxide triacrylate represented by the formula:



pentaerythritol tetraacrylate, dipentaerythritol pentaacrylate, dipentaerythritol hexaacrylate, and methacrylates corresponding to the above-mentioned acrylates.

5

Also, the present invention relates to the above-mentioned adhesive composition for a metal foil wherein the composition contains a polyvinyl acetal resin, a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule and an epoxy resin, said polyvinyl acetal resin comprises (a) an acetacetal portion, (b) a butylacetal portion, (c) a vinyl alcohol portion, (d) a vinyl acetate ester portion and (e) an itaconic acid portion having a carboxyl group as a side chain in the weight ratio of

10 $0.1 \leq (e) / ((a) + (b) + (c) + (d) + (e)) \leq 5$,
and an average degree of polymerization (a number average degree of polymerization, hereinafter the same, which is
20 determined by measuring, for example, a number average molecular weight of a polyvinyl acetate as a starting material utilizing a calibration curve of standard polystyrenes) of 1,000 to 3,000.

25 The present invention relates to the above-mentioned adhesive composition for a metal foil wherein the polyvinyl acetal resin comprises, in the weight ratio,

$0.3 < (a) / ((a) + (b))$ or
 $10 \leq (c) / ((a) + (b) + (c) + (d) + (e)) \leq 20$.

30

The present invention relates to the above-mentioned

adhesive composition for a metal foil which further comprises at least one filler selected from the group consisting of silica, alumina, aluminum hydroxide, magnesium hydroxide, talc and organic filler.

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The present invention relates to the above-mentioned adhesive composition for a metal foil which further comprises at least one of an antioxidant, a metal scavenger or a lubricant.

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Moreover, the present invention relates to an adhesive-coated metal foil which is obtained by coating the above-mentioned adhesive composition for a metal foil as a varnish on one of the surfaces of the metal foil and drying.

15

The present invention also relates to a metal-clad laminate obtained by laminating the adhesive layer side of the above-mentioned adhesive-coated metal foil on one surface or both surfaces of at least one sheet of a prepreg, and molding under heating and pressure.

20

The present invention further comprises a wiring board for forming a circuit on the metal surface of the above-mentioned metal-clad laminated board, a multi-layer board obtained by laminating the adhesive layer side of the above-mentioned adhesive-coated metal foil on the above wiring board as a circuit side and molding under heating and pressure, and a multi-layer wiring board which comprises forming a circuit on the metal surface of the multi-layer board.

30

DESCRIPTION OF THE PREFERRED EMBODIMENTS

35 In the following, the present invention is explained in detail.

The present invention relates to an adhesive composition for a metal foil which comprises a material wherein a tracking resistance test is carried out according to the IEC method by making a thickness of an adhesive layer 30 to 40 μm , using a copper foil pattern with a width of 4 mm and making a distance between electrodes 0.4 mm, then the adhesive layer dissolves out for the first time when 5 drops or more of an electrolyte are dropped thereon. When the above-mentioned tracking resistance test is carried out, if the adhesive layer dissolves out with less than 5 drops of the electrolyte, a prepreg layer under the adhesive layer is exposed. Tracking resistance of the prepreg layer is inferior to that of the adhesive layer so that good tracking resistance cannot be obtained when the adhesive layer dissolves out with less than 5 drops of the electrolyte. When the adhesive layer remains with 5 drops or more of electrolyte without dissolving out, then the adhesive layer maintain the level of the tracking resistance whereby higher tracking resistance can be obtained.

In the present invention, the adhesive composition for a metal foil preferably contains a polyvinyl acetal resin and a thermosetting resin.

As the thermosetting resin, an epoxy resin, a melamine resin, an isocyanate compound, a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule or the like is used.

The polyvinyl acetal resin to be used in the present invention is a polymer obtained by condensation of a polyvinyl alcohol and an aldehyde, and has an acetal bond in the molecule. When formaldehyde is used as an aldehyde, a polyvinyl formal resin can be obtained and butylaldehyde

is used as an aldehyde, a polyvinyl butyral resin can be obtained. In the present invention, the polyvinyl butyral resin is preferred. The degree of polymerization and a butyral component of the polyvinyl butyral resin are not particularly limited but preferably those having an average degree of polymerization of 500 to 3,000 and the butyral component of 60 mol % or more. If the average polymerization degree is less than 500, heat resistance of the adhesive is not sufficient, while if it exceeds 3,000, the viscosity of the adhesive becomes too high so that coating on a metal foil tend to be difficult. An amount of the butyral component is not particularly limited so long as it is within the above-mentioned range, but if it is less than 60 mol %, flexibility of the resin is not sufficient so that adhesive strength tends to be inferior.

As the polyvinyl butyral resin, commercially available products such as S-LEC BX-1 (average degree of polymerization: 1700, butyral component: 65 mol %), S-LEC BX-2 (average degree of polymerization: 1700, butyral component: 65 mol %), S-LEC BX-55 (average degree of polymerization: 1700, butyral component: 70 mol %) (all trade names, available from Sekisui Chemical Co., Ltd., Japan), Denka Butyral #4000-2 (average degree of polymerization: 1000, 75 % by weight, butyral component: 65 mol %), Denka Butyral #5000-A (average degree of polymerization: 2000, butyral component: 80 % by weight, 70 mol %), Denka Butyral #6000-C (average degree of polymerization: 2400, butyral component: 80 % by weight, 70 mol %) (all trade names, available from Denki Kagaku Kogyo K.K., Japan), and the like may be mentioned. These resins may be mentioned singly or in combination of two or more.

As the polyfunctional acrylate compound or the polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule, there may

be mentioned, for example, 1,4-butanediol diacrylate, 1,6-hexanediol diacrylate, 1,9-nonanediol diacrylate, neopentylglycol diacrylate, tetraethyleneglycol diacrylate, tripropyleneglycol diacrylate, polypropylene glycol
5 diacrylate, ethylene glycol diacrylate, diethylene glycol diacrylate, triethylene glycol diacrylate, polyethylene glycol diacrylate, bisphenol A ethylene oxide-modified diacrylate, pentaerythritol triacrylate, trimethylolpropane triacrylate, trimethylolpropane ethylene oxide
10 triacrylate (shown by the above formula), trimethylolpropane propylene oxide triacrylate (shown by the above formula), trisacryloyloxyethyl phosphate, isocyanuric acid ethylene oxide triacrylate (shown by the above formula), pentaerythritol tetraacrylate, dipentaerythritol penta-
15 acrylate, dipentaerythritol hexaacrylate and methacrylates corresponding to the above-mentioned acrylates, and the like. Among these compounds, in the point of heat resistance of the cured product, preferred are those having three or more of acryloyl groups or methacryloyl groups in
20 the molecule such as pentaerythritol triacrylate, trimethylolpropane triacrylate, trimethylolpropane ethylene oxide triacrylate, trimethylolpropane propylene oxide triacrylate, trisacryloyloxyethyl phosphate, isocyanuric acid ethylene oxide triacrylate, pentaerythritol tetra-
25 acrylate, dipentaerythritol pentaacrylate, dipentaerythritol hexaacrylate and methacrylates corresponding to the above-mentioned acrylates.

The epoxy resin to be used in the present invention is not
30 particularly limited, and there may be used a bisphenol A type epoxy resin, a bisphenol AF type epoxy resin, a bisphenol F type epoxy resin, a bisphenol S type epoxy resin, a bisphenol AD type epoxy resin, a phenol-novolak type epoxy resin, a cresol-novolak type epoxy resin, an aliphatic epoxy resin, an alicyclic epoxy resin, a glycidyl
35 ester type epoxy resin, a glycidyl amine type epoxy resin,

- a heterocyclic epoxy resin, an epoxidized polybutadiene resin and the like. More specifically, commercially available products such as Epikote 815, 828, 1001, 1004 and 1007 (all trade names, available from Yuka Shell Epoxy K.K., Japan, bisphenol A type epoxy resins), Epikote 152 and 154 (all trade names, available from Yuka Shell Epoxy K.K., Japan, phenol-novolak type epoxy resins), Epikote 180S65 (trade name, available from Yuka Shell Epoxy K.K., Japan, cresol-novolak type epoxy resin), EX-611 and 612 (all trade names, available from Nagase Kasei Kogyo K.K., Japan, aliphatic epoxy resins), CY175, 177 and 179 (all trade names, available from Asahi Ciba K.K., Japan, alicyclic epoxy resins), Epikote 871 and 872 (all trade names, available from Yuka Shell Epoxy K.K., Japan, glycidyl ester type epoxy resins), TETRAD-X and TETRAD-C (all trade names, available from Mitsubishi Gas Chemical Co., Inc., Japan, glycidyl amine type epoxy resins), TEPIC (trade name, available from Nissan Chemical Industries, Ltd., Japan, heterocyclic epoxy resin), BF-1000 (trade name, available from ASAHI DENKA KOGYO K.K., Japan, epoxidized polybutadiene resin) and the like may be used. These epoxy resins may be used singly or in combination of two or more.
- 25 In the present invention, a curing agent for the polyfunctional acrylate compound or the polyfunctional methacrylate compound may be used, if necessary. The curing agent is not particularly limited and may be mentioned an organic peroxide, etc. Representative examples thereof
- 30 may include methyl ethyl ketone peroxide, cyclohexanone peroxide, 1,1-bis(t-hexylperoxy)cyclohexanone, cumene hydroperoxide, dicumyl peroxide, t-butylcumyl peroxide, isobutyl peroxide, octanoyl peroxide, lauroyl peroxide, benzoyl peroxide, diisopropyl peroxydicarbonate, cumyl peroxyneodecanate and the like. An amount of the curing
- 35 agent to be used is preferably 0.1 to 10 % by weight based

on the amount of the polyfunctional acrylate compound or the polyfunctional methacrylate compound.

- Also, in the present invention, a curing agent or a curing accelerator for an epoxy resin may be used, if necessary. The kind and the amount of the curing agent are not particularly limited. The curing agent or the curing accelerator for an epoxy resin may include an amine series curing agent such as 4,4'-diaminodiphenylmethane, etc.; an imidazole series curing agent or curing accelerator such as 2-ethyl-4-methylimidazole, etc.; and a Lewis acid series curing agent such as BF_3 monoethylamine complex, etc. An amount of the curing agent to be used is preferably 0.5 to 2 equivalent, more preferably 1 equivalent or substantially 1 equivalent based on 1 equivalent of the epoxy group of the epoxy resin. An amount of the curing accelerator is preferably 0.1 to 10 % by weight based on the amount of the epoxy resin.
- The melamine resin to be used in the present invention is not particularly limited, and may be mentioned a methyl etherified melamine resin, a butyl etherified melamine resin, a mixed etherified melamine resin and the like. More specifically, commercially available products such as MS-11, MS-001, MW-30 and MX-705 (all trade names, available from Sanwa Chemical Co., Japan, methyl etherified melamine resins), Melan 220, Melan 245, Melan 280 and Melan 2000 (all trade names, available from Hitachi Chemical Co., Ltd., Japan, butyl etherified melamine resins), and MX-408 (trade name, available from Sanwa Chemical Co., Japan, mixed etherified melamine resins) may be used. These melamine resins may be used singly or in combination of two or more. Moreover, a curing agent for such melamine resins may be also used, if necessary. The kind and the amount of the curing agent are not particularly limited, but the amount thereof is preferably 0.1 to

10 % by weight based on the amount of the melamine resin. The curing agent may include, for example, an acidic curing agent such as p-toluenesulfonic acid, adipic acid, itaconic acid, salicylic acid, oxalic acid, benzoic acid, 5 acetic acid, etc., and an acid anhydride series curing agent such as maleic anhydride, phthalic anhydride, acetic anhydride, etc.

The isocyanate compound to be used in the present invention is not particularly limited, and preferably a block isocyanate in which an isocyanate is blocked with a compound having an active hydrogen in view of storage stability of the adhesive. The isocyanate may include hexamethylene diisocyanate, tolylene diisocyanate, 15 diphenylmethane diisocyanate, isophorone diisocyanate, and the like, but it is not specifically limited to these so long as desired characteristics can be obtained. More specifically, commercially available block isocyanates such as CORONATE AP stable, CORONATE 2503, Millionate MS- 20 50, CORONATE 2515, CORONATE 2517, CORONATE 2512, CORONATE 2507, CORONATE 2527, CORONATE 2513, CORONATE 2529 (all trade names, available from NIPPON POLYURETHANE INDUSTRY, CO., LTD., Japan) may be used.

25 In the present invention, the adhesive composition for a metal foil preferably comprises a polyvinyl acetal resin and a thermosetting resin, and in the thermogravimetric analysis after curing, a 5 % weight loss temperature is 290°C or more and a carbon residual ratio at 650°C is less 30 than 1 % by weight.

The method for the thermogravimetric analysis is not particularly limited, and the method with a temperature-raising rate of 5°C/min to 10°C/min is generally used. 35 The 5 % weight loss temperature of the cured reaction product is required to be 290°C or more. If it is less

than 290°C, the desired high tracking property cannot be obtained. Moreover, the carbon residual ratio at 650°C is required to be less than 1 % by weight. If the carbon residual ratio is 1 % by weight or more, the desired high tracking property cannot be obtained.

A formulation ratio of the polyvinyl acetal resin and the thermosetting resin is preferably the former/the latter of 25/100 to 600/100 (weight ratio).

10

Further, in the present invention, it is preferred that at least one of thermosetting resins does not react with a polyvinyl acetal resin and it is compatible with the polyvinyl acetal resin uniformly. If the thermosetting resin reacts with the polyvinyl acetal resin, reaction form becomes complex and sufficient reactivity is tend to be difficultly obtained. Also, when the thermosetting resin and the polyvinyl acetal resin are not compatible uniformly, the composition of the cured product becomes ununiform and the heat resistance, etc. are tend to be lowered.

Moreover, in the present invention, it is preferred that at least one of thermosetting resins does not have an aromatic ring. When it has an aromatic ring, the carbon residual ratio at 650°C tends to be easily 1 % by weight or more and the tracking resistance is tend to be lowered.

In the present invention, it is preferred that at least one of the thermosetting heat-resistant resins is at least one of a polyfunctional acrylate compound or a polyfunctional methacrylate compound having at least 2 of an acryloyl group or a methacryloyl group in the molecule.

In the present invention, it is preferred that the above-mentioned adhesive composition for a metal foil comprises

as main components a polyvinyl acetal resin, a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule and an epoxy resin.

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The formulation ratio of the main components of the adhesive composition for a metal foil according to the present invention is preferably, based on 100 parts by weight of a polyvinyl acetal resin, 20 to 500 parts by weight of a polyfunctional acrylate compound or a polyfunctional methacrylate compound, and 5 to 100 parts by weight of an epoxy resin. If the formulation amount of the polyfunctional acrylate compound or the polyfunctional methacrylate compound is less than 20 parts by weight, curing of the resin tends to be insufficient whereby the heat resistance of the cured product tends to be low. If it exceeds 500 parts by weight, peeling strength of the metal foil tends to be lowered. If an amount of the epoxy resin is less than 5 parts by weight, metal peeling strength is lowered while if it exceeds 100 parts by weight, the resin after curing tends to become brittle. The amount of the epoxy resin is preferably within the range of 10 to 80 parts by weight.

25 Incidentally, in the present invention, a thermosetting resin such as a melamine resin, a polyester, a phenol resin, a polyurethane resin, an isocyanate resin and the like may be added to the above-mentioned adhesive composition for a metal foil within the range which does not impair the characteristics of the cured product.

The thermosetting resin other than the epoxy resin is preferably used in an amount of 20 % by weight or less based on the total amount of the thermosetting resin such as the polyvinyl acetal resin, epoxy resin, etc. and the polyfunctional (meth)acrylate compound, and the melamine

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resin is preferably used in an amount of 3 to 20 % by weight based on the same to avoid tackiness of the composition.

- 5 Also, in the present invention, it is preferred that the above-mentioned adhesive composition for a metal foil contains a polyvinyl acetal resin, a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule and an epoxy resin, said polyvinyl
10 acetal resin comprises (a) an acetacetal portion, (b) a butylacetal portion, (c) a vinyl alcohol portion, (d) a vinyl acetate ester portion and (e) an itaconic acid portion having a carboxyl group as a side chain in the
15 weight ratio of

$$0.1 \leq (e) / ((a) + (b) + (c) + (d) + (e)) \leq 5,$$
and an average degree of polymerization thereof is 1,000 to 3,000.

- 20 According to the above formulation, tracking resistance and solder heat resistance can be improved. If the formulation ratio is less than the above-mentioned range, heat resistance tends to be lowered, while if it exceeds the above range, solubility tends to be lowered. If the
25 above-mentioned average degree of polymerization is less than 1,000, heat resistance tends to be lowered, while if it exceeds 3,000, the viscosity of the varnish becomes high so that it is disadvantageous to prepare a composition with a higher amount of resin.

- 30 When the polyvinyl acetal resin satisfies, in a weight ratio,

$$0.3 < (a) / ((a) + (b)) \text{ or}$$

$$10 \leq (c) / ((a) + (b) + (c) + (d) + (e)) \leq 20,$$

- 35 tracking resistance, solder heat resistance and compatibility of the resins are more improved.

Also, in the present invention, it is preferred to formulate, as a filler, at least one selected from selected from the group consisting of silica, alumina, aluminum hydroxide, magnesium hydroxide, talc and organic filler.

5 The kind and the shape of the filler are not particularly limited, and aluminum hydroxide is preferred to give good tracking resistance. It is preferred to formulate, as an additive, at least one of an antioxidant, a metal scavenger or a lubricant. The antioxidant is not particular-

10 ly limited, and is preferably at least one selected from the group consisting of a monophenol type, a bisphenol type, a trisphenol type, a polyphenol type and a hindered phenol type ones. If these antioxidants are not added, metal foil peeling strength or solder heat resistance may

15 sometimes be lowered. Also, the metal scavenger is not particularly limited, and is preferably at least one selected from the group consisting of an oxine and its derivatives, a triazine thiol and its derivatives. By adding these compounds, further improvement in tracking

20 resistance can be expected. Moreover, the lubricant is also not particularly limited, and is preferably at least one selected from the group consisting of a silicone compound and a fluorine compound. By adding these compounds, the step of preparing or using the adhesive-coated metal

25 foil can be easily automated.

The adhesive composition for a metal foil of the present invention is dissolved in an organic solvent to produce a varnish and the varnish is coated on one side surface of

30 the metal foil and dried to obtain an adhesive-coated metal foil. As the organic solvent, it is not particularly limited so long as it dissolves the above-mentioned material, and there may be mentioned, for example, an alcohol series solvent such as methanol, ethanol, iso-

35 propanol, n-butanol, etc; a ketone series solvent such as acetone, methyl ethyl ketone, cyclohexanone, etc.; an

aromatic hydrocarbon solvent such as toluene, xylene, etc.; a sulfur compound series solvent such as dimethylsulfoxide, etc.; an amide series solvent such as N-methylpyrrolidone, formaldehyde, N-methylformaldehyde, N,N-dimethylformamide, etc.; a cellosolve series solvent such as methyl cellosolve, ethyl cellosolve, and cellosolve acetate, and the like.

10 The metal foil to be used for preparing the adhesive-coated metal foil according to the present invention is not particularly limited, and any metal foil usually used for a laminated plate such as a copper foil, an aluminum foil, etc. having a thickness of 5 to 200 μm may be used. Also, a three-layered structure composite foil comprising
15 an intermediate layer such as nickel, nickel-phosphor, a nickel-tin alloy, a nickel-iron alloy, lead, a lead-tin alloy, etc. being interposed between a copper layer having a thickness of 0.5 to 15 μm and a copper layer having a thickness of 10 to 300 μm , or a composite foil in which an
20 aluminum foil and a copper foil are laminated may be used.

The adhesive-coated metal foil according to the present invention can be obtained by coating the above-mentioned varnish on the one surface of the metal foil and drying.
25 An amount of the adhesive to be coated on the metal foil is not particularly limited and it is preferred to make the thickness of the adhesive layer after drying 10 to 200 μm .
30 If the thickness of the adhesive layer is less than 10 μm , metal peeling strength is lowered while if it exceeds 200 μm , an amount of the remaining non-volatile component becomes large whereby heat resistance tends to be lowered. The thickness of the adhesive layer is preferably 20 to
35 100 μm , more preferably 25 to 80 μm .

For heating and drying means, hot air drying, far infrared drying, etc. may be used, and it is not particularly limited. Also, the drying temperature and the drying time are not particularly limited, and they are preferably in the range of 40 to 250°C with the drying time of 10 seconds to 20 minutes. The residual non-volatile component of the adhesive layer is preferably 10 % by weight or less.

- 10 The metal-clad laminate of the present invention can be produced by coating the varnish of the above-mentioned adhesive composition for a metal foil on the one surface of the metal foil and drying to prepare an adhesive-coated metal foil, laminating the adhesive surface of the
- 15 adhesive-coated metal foil to one surface or both surfaces of a core material or a prepreg at least one of which is laminated, and molding the resulting material under vacuum or a normal pressure and under heating and pressure. Molding is carried out at the heating temperature
- 20 preferably within the range of 80 to 200°C and the pressure generally within the range of 1 to 15 MPa for 30 to 180 minutes.

- 25 The adhesive-coated metal foil of the present invention can be used as a material for multi-layer of the so-called build-up method in which the foil is laminated to an inner layer plate by the heat press method or the heat roll laminate method when a thin multi-layer wiring board is to be produced.

- 30 As the base material for the prepreg to be used for producing the metal-clad laminate of the present invention, paper, a glass cloth, an aramid cloth and non-woven fabric thereof may be used. As the thermosetting resin to be
- 35 used as a matrix of the prepreg, a phenol resin, an epoxy resin, a polyimide resin, an unsaturated polyester resin,

etc. may be used.

A wiring board can be produced by printing an electric circuit on the metal surface of the metal-clad laminate by using a resist ink or a resist film, and removing the metal at the portion of no resist by etching to form a wiring board.

The adhesive layer of the adhesive-coated metal foil of the present invention is adhered onto the circuit side(s) of the one surface or both surfaces of the wiring board obtained as mentioned above or the conventional wiring board, and molding the resulting material under vacuum or under normal pressure and under heating and pressure, whereby a multi-layer board can be produced. Also, a highly multi-layered multi-layer plate can be produced by subjecting the surface of the above-mentioned multi-layer board to circuit fabrication, laminating the adhesive-coated metal foil in the same manner, and molding under heating and pressure, and repeating these procedure.

Moreover, a multi-layer wiring board can be produced by forming a circuit on the metal surface of the multi-layer board according to the conventional manner.

EXAMPLES

In the following, the present invention will be explained by referring to Examples but the present invention is not limited by these Examples. In the following Examples, "part" means "part by weight", and "%" means "% by weight".

Examples 1 and 2

Resins formulated as shown in Table 1 (the unit is a part

by weight, hereinafter the same in Examples and Comparative examples) were uniformly dissolved in a mixed solvent of methanol-methyl ethyl ketone (1/1 weight ratio) and the solid component of the resulting material was regulated to
5 as 30 % to obtain a varnish of an adhesive composition for metal foil. This varnish was coated on one surface of a copper foil having a thickness of 35 μm by a roll coater and thermally dried and cured at 160°C for 5 minutes to obtain an adhesive-coated copper foil with the adhesive
10 layer thickness of 40 μm . On the adhesive side of the above copper foil were placed 8 sheets of phenol resin-impregnated paper base materials (B stage (semi-cured at 150 °C for 5 minutes) tung oil-modified phenol resin-impregnated craft paper, in the following Examples, the
15 same material was used) to prepare a laminate, and the resulting material was sandwiched between stainless mirror plates and molded under heating at 160 °C, at a pressure of 10 MPa for 60 minutes to obtain a copper-clad laminate. The characteristics of this copper-clad laminate were
20 shown in Table 1.

The tung oil-modified phenol resin used for the impregnated paper base material was prepared as mentioned below.

25 A mixture comprising 1,500 g of phenol, 1,000 g of tung oil and 3 g of p-toluenesulfonic acid were reacted at 90°C for 3 hours, then, 800 g of a 80% paraformaldehyde and 50 g of a 25 % aqueous ammonia were added thereto, and the mixture was reacted at 75°C for 3 hours. Next, the reaction mixture was concentrated under reduced pressure at
30 80°C, the condensed water was removed and the point when the gel time at 160°C became 150 seconds was made a final point. The resulting material was diluted by a mixed solvent (toluene-methanol (1/1 weight ratio)) to prepare a
35 tung oil-modified phenol resin varnish having a resin content of 50 %.

Comparative examples 1 and 2

In the same manner as in Example 1 except for changing the materials to be used as shown in Table 1, varnish samples as shown in Table 1 were prepared and their properties were also measured in the same manner as in Examples.

Table 1

Item	Examples		Comparative examples	
	1	2	1	2
S-LEC BX-1	100	100	100	100
Epikote 180S65	40	40	30	30
Melan 2000	—	20	70	—
VP-13N	—	—	—	70
Pentaerythritol tetraacrylate	80	80	40	—
Dicumyl peroxide	0.8	0.8	—	—
Benzoic acid	—	—	0.7	—
Number of drops until adhesive layer dissolved out (drops, 200 V)	15	14	3	1 (tracking resistance breakage)
5% weight loss temperature (°C) of cured adhesive	310	295	275	300
Carbon residual ratio (%) of cured adhesive at 650°C	0.5	0.6	0.7	3.5
Solder heat resistance (sec)	51	55	48	40
Copper foil peeling strength (kN/m)	1.9	1.8	1.8	1.9
High temperature (150°C)	0.6	0.7	0.5	0.6
Tracking resistance (V)	260 or more	260 or more	200	110

10

S-LEC BX-1: trade name, available from Sekisui Chemical Co., Ltd., polyvinyl acetal resin, average degree of polymerization: 1700, butyral component: 65 mol %.

Epikote 180S65: trade name, available from Yuka Shell
Epoxy K.K., cresol-novolak type epoxy resin.
Melan 2000: trade name, available from Hitachi Chemical
Co., Ltd., n-butylated melamine resin.
5 VP-13N: trade name, available from Hitachi Chemical Co.,
Ltd., resol type phenol resin.

Solder heat resistance and copper foil peeling strength
were measured according to JIS C6481. Tracking resistance
10 was measured according to the IEC method by using a
platinum electrode with a copper foil pattern of 4 mm
width pattern and the distance between the electrodes of
0.4 mm (hereinafter the same).

15 As can be seen from the above Table 1, in the results of
each Example, solder heat resistance is good, tracking
resistance is excellent and lowering in other character-
istics are not observed as compared with those of the
comparative examples.

20 Examples 3 to 6

Resins formulated as shown in Table 2 were uniformly
dissolved in a mixed solvent of methanol-methyl ethyl
25 ketone (1/1 weight ratio) and the solid component of the
resulting material was regulated to as 30 % to obtain a
varnish of an adhesive composition for metal foil. This
varnish was coated on one surface of a copper foil having
a thickness of 35 μm by a roll coater and thermally dried
30 and cured at 160°C for 5 minutes to obtain an adhesive-
coated copper foil with the adhesive layer thickness of 40
 μm . On the adhesive side of the above copper foil were
placed 8 sheets of phenol resin-impregnated paper base
materials to prepare a laminate, and the resulting materi-
35 al was sandwiched between stainless mirror plates and
molded under heating at 160 °C, at a pressure of 10 MPa

for 60 minutes to obtain a copper-clad laminate. The characteristics of this copper-clad laminate were shown in Table 2.

5 Comparative examples 3 and 4

In the same manner as in Example 3 except for changing the materials to be used as shown in Table 2, varnish samples as shown in Table 2 were prepared and their properties were also measured in the same manner as in Examples.

Table 2

Item	Examples				Comparative examples	
	3	4	5	6	3	4
S-LEC BX-1	100	100	100	100	100	100
Epikote 180S65	40	40	40	40	30	30
Melan 2000	—	20	—	—	70	—
VP-13N	—	—	—	—	—	70
Pentaerythritol tetraacrylate	80	80	80	80	—	—
CORONATE 2515	—	—	20	—	—	—
Aluminum hydroxide	—	—	—	100	—	—
Dicumyl peroxide	0.8	0.8	0.8	0.8	—	—
Benzoic acid	—	—	—	—	0.7	—
Number of drops until adhesive layer dissolved out (drops, 200 V)	15	14	14	17	3	1
5% weight loss temperature (°C) of cured adhesive	310	295	305	310	260	300
Carbon residual ratio (%) of cured adhesive at 650°C	0.5	0.8	0.6	0.5	0.9	3.5
Solder heat resistance (sec)	51	55	48	50	35	40
Copper foil peeling strength (kN/m)	1.9	1.8	1.8	1.9	1.9	1.9
High temperature (150°C)	0.6	0.7	0.8	1.0	0.4	0.6
Tracking resistance (V)	260 or more	260 or more	260 or more	260 or more	200	110

S-LEC BX-1: trade name, available from Sekisui Chemical Co., Ltd., polyvinyl acetal resin, average degree of polymerization: 1700, butyral component: 65 mol %.

Epikote 180S65: trade name, available from Yuka Shell Epoxy K.K., cresol-novolak type epoxy resin.

Melan 2000: trade name, available from Hitachi Chemical Co., Ltd., n-butylated melamine resin.

VP-13N: trade name, available from Hitachi Chemical Co.,

Ltd., resol type phenol resin.

CORONATE 2515: trade name, available from NIPPON

POLYURETHANE INDUSTRY, CO., LTD., block
isocyanate.

5

As can be seen from the above Table 2, in the results of
each Example, solder heat resistance is good, tracking
resistance is excellent and lowering in other character-
istics are not observed as compared with those of the
10 comparative examples.

Examples 7 to 9

Resins formulated as shown in Table 3 were uniformly dis-
solved in a mixed solvent of methanol-methyl ethyl ketone
15 (1/1 weight ratio) and the solid component of the result-
ing material was regulated to as 30 % to obtain a varnish
of an adhesive composition for metal foil. This varnish
was coated on one surface of a copper foil having a thick-
ness of 35 μm by a roll coater and thermally dried and
20 cured at 160°C for 5 minutes to obtain an adhesive-adhered
copper foil with the adhesive layer thickness of 40 μm .
On the adhesive side of the above copper foil were placed
8 sheets of phenol resin-impregnated paper base materials
25 to prepare a laminate, and the resulting material was
sandwiched between stainless mirror plates and molded
under heating at 160 °C, at a pressure of 10 MPa for 60
minutes to obtain a copper-clad laminate. The character-
istics of this copper-clad laminate were shown in Table 3.

30

Comparative examples 5 and 6

In the same manner as in Example 7 except for changing the
materials to be used as shown in Table 3, varnish samples
35 as shown in Table 3 were prepared and their properties
were also measured in the same manner as in Examples.

Table 3

Item	Examples			Comparative examples	
	7	8	9	5	6
Denka Butyral #5000-A	100	100	100	100	100
Epikote 180S65	20	50	80	30	30
Melan 2000	—	—	—	70	—
VP-13N	—	—	—	—	70
Pentaerythritol triacrylate	80	—	—	—	—
Isocyanuric acid ethyleneoxide-modified triacrylate	—	100	—	—	—
Dipentaerythritol pentaacrylate	—	—	450	—	—
Dicumyl peroxide	0.5	1.0	4.5	—	—
Benzoic acid	—	—	—	0.7	—
Number of drops until adhesive layer dissolved out (drops, 200 V)	14	15	15	3	1
Solder heat resistance (sec)	51	55	60	35	39
Copper foil peeling strength (kN/m)	1.9	1.8	1.8	1.9	1.9
High temperature (150°C)	0.6	0.7	0.8	0.4	0.6
Tracking resistance (V)	260 or more	260 or more	260 or more	200	110

5 Denka Butyral #5000-A: trade name, available from Denki Kagaku Kogyo K.K., polyvinyl acetal resin, average degree of polymerization: 2000, butyral component: 70 mol %.

Epikote 180S65: trade name, available from Yuka Shell

10 Epoxy K.K., cresol-novolak type epoxy resin.

Melan 2000: trade name, available from Hitachi Chemical Co., Ltd., n-butyrlated melamine resin.

VP-13N: trade name, available from Hitachi Chemical Co., Ltd., resol type phenol resin.

As can be seen from the above Table 3, in the results of each Example, solder heat resistance is good, tracking resistance is excellent and lowering in other characteristics are not observed as compared with those of the comparative examples.

Examples 10 and 11

To 100 parts of a polyvinyl acetal resin (S-LEC KS-31Z, trade name, available from Sekisui Chemical Co., Ltd.), 70 parts of pentaerythritol triacrylate as a polyfunctional acrylate resin, 30 parts of a cresol-novolak type epoxy resin (Epikote 180S65, trade name, available from Yuka Shell Epoxy K.K.) as an epoxy resin, 3 parts of dicumyl peroxide, 3 parts of pyrrogalol as an antioxidant, 1 part of dibutylaminotriazine dithiol as a metal scavenger and 0.5 part of BYK-333 (trade name, a silicon series compound, available from Big Chemie Japan) as a lubricant were formulated. These materials were uniformly dissolved in a mixed solvent of methanol-methyl ethyl ketone (1/1 weight ratio) and the solid component of the resulting material was regulated to as 30 % to obtain a varnish. This varnish was coated on one surface of a copper foil having a thickness of 35 μm by a roll coater and thermally dried and cured at 160°C for 5 minutes to obtain an adhesive-coated copper foil with the adhesive layer thickness of 40 μm . On the adhesive side of the above copper foil were placed 8 sheets of phenol resin-impregnated paper base materials to prepare a laminate, and the resulting material was sandwiched between stainless mirror plates and molded under heating at 160 °C, at a pressure of 10 MPa for 60 minutes to obtain a copper-clad laminate. The characteristics of this copper-clad laminate were shown in Table 4.

Table 4

Item	Examples	
	10	11
Acetal portion (weight %)	72	72
(a) Acetacetal portion (weight %)	40	80
(b) Vinyl alcohol portion (weight %)	13	13
(c) Acetic acid vinyl ester portion (weight %)	15	15
(d) Acid portion of side chain (weight %)	1	1
Kind of acid at side chain	Itaconic acid	Itaconic acid
Number average degree of polymerization	1500	2000
Number of drops until adhesive layer dissolved out (drops, 200 V)	14	14
Solder heat resistance (sec)	40	43
Copper foil peeling strength (kN/m)	2.1	2.1
High temperature (150°C)	0.6	0.7
Tracking resistance (V)	260 or more	260 or more

As can be seen from the above Table 4, in the results of each Example, solder heat resistance is good, tracking resistance is excellent and lowering in other characteristics are not observed.

In the adhesive-coated metal foil, the metal-clad laminate, the wiring board, the multi-layer board and the multi-layer wiring board using the adhesive composition for a metal foil of the present invention, solder heat resistance is good, tracking resistance is excellent and lowering in other characteristics are not observed so that their industrial values are extremely large.

Claims:

1. An adhesive composition for a metal foil which comprises a material wherein a tracking resistance test is carried out according to the IEC method by making a thickness of an adhesive layer 30 to 40 μm , using a copper foil pattern with a width of 4 mm and making a distance between electrodes 0.4 mm, then the adhesive layer dissolves out for the first time when 5 drops or more of an electrolyte are dropped thereon.
2. The adhesive composition for a metal foil according to Claim 1, wherein said composition comprises a polyvinyl acetal resin and a thermosetting resin.
3. An adhesive composition for a metal foil which comprises a polyvinyl acetal resin and a thermosetting resin and in a thermogravimetric analysis after curing, a 5 % weight loss temperature being 290°C or more and a carbon residual ratio at 650°C being less than 1 % by weight.
4. The adhesive composition for a metal foil according to Claim 3, wherein said composition comprises thermosetting resins at least one of which does not react with a polyvinyl acetal resin and which is compatible with the polyvinyl acetal resin uniformly.
5. The adhesive composition for a metal foil according to Claim 4, wherein said composition comprises thermosetting resins at least one of which does not have an aromatic ring.
6. The adhesive composition for a metal foil according to Claim 4, wherein said composition comprises thermosetting heat-resistant resins at least one of which is at least one of a polyfunctional acrylate compound or a polyfunc-

tional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule.

7. An adhesive composition for a metal foil which comprises as main components a polyvinyl acetal resin, a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule and an epoxy resin.
- 10 8. The adhesive composition for a metal foil according to Claim 7, wherein said composition comprises 20 to 500 parts by weight of a polyfunctional acrylate compound or a polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule and
- 15 5 to 100 parts by weight of an epoxy resin based on 100 parts by weight of a polyvinyl acetal resin.
9. The adhesive composition for a metal foil according to Claim 7, wherein the polyfunctional acrylate compound or
- 20 the polyfunctional methacrylate compound having two or more acryloyl groups or methacryloyl groups in the molecule is at least one selected from the group consisting of pentaerythritol triacrylate, trimethylolpropane triacrylate, trimethylolpropane ethyleneoxide-modified triacrylate, trimethylolpropane propyleneoxide-modified triacrylate, triacryloyloxyethyl phosphate, isocyanuric acid
- 25 ethylene oxide-modified triacrylate, pentaerythritol tetraacrylate, dipentaerythritol pentaacrylate, dipentaerythritol hexaacrylate, and methacrylates corresponding
- 30 to the above-mentioned acrylates.
10. An adhesive composition for a metal foil which comprises a polyvinyl acetal resin, a polyfunctional acrylate compound or a polyfunctional methacrylate compound having
- 35 two or more acryloyl groups or methacryloyl groups in the molecule and an epoxy resin, wherein said polyvinyl acetal

resin comprises (a) an acetacetal portion, (b) a butyl-acetal portion, (c) a vinyl alcohol portion, (d) a vinyl acetate ester portion and (e) an itaconic acid portion having a carboxyl group as a side chain in the weight ratio of

$0.1 \leq (e) / ((a) + (b) + (c) + (d) + (e)) \leq 5$,
and a number average degree of polymerization of 1,000 to 3,000.

- 10 11. The adhesive composition for a metal foil according to Claim 10, wherein the polyvinyl acetal resin comprises, in the weight ratio,

$$0.3 < (a) / ((a) + (b)) \text{ or}$$

15 $10 \leq (c) / ((a) + (b) + (c) + (d) + (e)) \leq 20$.

12. The adhesive composition for a metal foil according to any one of Claims 1 to 11, wherein said composition further comprises at least one filler selected from the group consisting of silica, alumina, aluminum hydroxide, magnesium hydroxide, talc and organic filler.

13. The adhesive composition for a metal foil according to any one of Claims 1 to 11, wherein said composition further comprises at least one of an antioxidant, a metal scavenger or a lubricant.

14. An adhesive-coated metal foil which is obtained by coating the adhesive composition for a metal foil according to any one of Claims 1 to 11 as a varnish on one of the surfaces of the metal foil and drying.

15. A metal-clad laminate obtained by laminating the adhesive layer side of the adhesive-coated metal foil according to Claim 13 on one surface or both surfaces of at least one sheet of a prepreg, and molding under heating and pressure.

16. A wiring board for forming a circuit on the metal surface of the metal-clad laminated board according to Claim 15.

5 17. A multi-layer board obtained by laminating the adhesive layer side of the adhesive-coated metal foil according to Claim 14 on a wiring board as a circuit side and molding the resulting material under heating and pressure.

10

18. A multi-layer wiring board which comprises forming a circuit on the metal surface of the multi-layer board according to Claim 17.

Abstract:

Disclosed are an adhesive composition for a metal foil which comprises a material wherein a tracking resistance test is carried out according to the IEC method by making a thickness of an adhesive layer 30 to 40 μm , using a copper foil pattern with a width of 4 mm and making a distance between electrodes 0.4 mm, then the adhesive layer dissolves out for the first time when 5 drops or more of an electrolyte are dropped thereon,

an adhesive-coated metal foil, a metal-clad laminate, a wiring board, a multi-layer board and a multi-layer wiring board using the same.

DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name, I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

ADHESIVE COMPOSITION FOR METAL FOIL, AND ADHESIVE-COATED METAL FOIL, METAL-CLAD
LAMINATE AND RELATED MATERIALS USING THE SAME

the specification of which (check one)

☒

is attached hereto.

☐

was filed on _____
as Application Serial No. _____
and was amended on _____

(if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

<u>269692/1998</u> (Number)	<u>Japan</u> (Country)	<u>24/September/1998</u> (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status: patented, pending, abandoned)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status: patented, pending, abandoned)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status: patented, pending, abandoned)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status: patented, pending, abandoned)

(Continued on Page 2)

I hereby appoint as principal attorneys; Donald R. Antonelli, Reg. No. 20,296; David T. Terry, Reg. No. 20,178; Melvin Kraus, Reg. No. 22,466; Stanley A. Wal, Reg. No. 26,432; William I. Solomon, Reg. No. 28,565; Gregory E. Montone, Reg. No. 28,141; Ronald J. Shore, Reg. No. 28,577; Donald E. Stout, Reg. No. 26,422; Alan E. Schiavelli, Reg. No. 32,087; James N. Dresser, Reg. No. 22,973 and Carl I. Brundidge, Reg. No. 29,621 to prosecute and transact all business connected with this application and any related United States application and international applications. Please direct all communications to the following address:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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**CHANGE OF
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Application Number	
Filing Date	September 24, 1999
First Named Inventor	Toshihisa KUMAKURA
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Date

September 24, 1999

